

# EQRA25P1H-11.113M

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## REGULATORY COMPLIANCE (Data Sheet downloaded on Jun 1, 2020)



◀ Click badges to download compliance docs

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



## ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.0Vdc 6 Pad 3.2mm x 5.0mm Ceramic Surface Mount (SMD) 11.113MHz ±50ppm over -40°C to +105°C

## ELECTRICAL SPECIFICATIONS

Nominal Frequency	11.113MHz
Frequency Tolerance/Stability	±50ppm Maximum over -40°C to +105°C (Inclusive of all conditions: Calibration Tolerance (at 25°C), Frequency Stability over the Operating Temperature Range, Supply Voltage Change and Output Load Change)
Aging at 25°C	±2ppm Maximum First Year, ±10ppm/10 Years Maximum
Supply Voltage	3.0Vdc ±5%
Input Current	20mA Maximum (Unloaded)
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH = -4mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL = +4mA)
Rise/Fall Time	3nSec Maximum (Measured at 10% to 90% of Waveform)
Duty Cycle	50 ±10(%) (Measured at 50% of Waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Phase Noise	-64dBc/Hz at 10Hz offset; -96dBc/Hz at 100Hz offset; -124dBc/Hz at 1kHz offset; -131dBc/Hz at 10kHz offset; -132dBc/Hz at 100kHz offset; -149dBc/Hz at 1MHz offset; -157dBc/Hz at 10MHz offset; -159dBc/Hz at 20MHz offset (All Values are Typical)
Output Control Function	Output Enable (OE)
Output Control Input Voltage Logic High (Vih)	90% of Vdd Minimum or No Connect to Enable Output
Output Control Input Voltage Logic Low (Vil)	10% of Vdd Maximum to Disable Output (High Impedance)
Output Enable Time	100nSec Maximum
Output Disable Time	50nSec Maximum
Output Enable Current	15mA Maximum (Without Load (Pin 1 = Ground))
RMS Phase Jitter	1.5pSec Maximum (Fj=12kHz to 20MHz (Random))
Period Jitter (Deterministic)	0.2pSec Typical
Period Jitter (Random)	2pSec Typical
Period Jitter (RMS)	3pSec Maximum
Period Jitter (pk-pk)	30pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K

**EQRA25P1H-11.113M** [Click part number to visit Part Number Details page](#)**ENVIRONMENTAL & MECHANICAL SPECIFICATIONS CONTINUED**

<b>Resistance to Solvents</b>	MIL-STD-202, Method 215
<b>Solderability</b>	MIL-STD-883, Method 2003
<b>Temperature Cycling</b>	MIL-STD-883, Method 1010, Condition B
<b>Vibration</b>	MIL-STD-883, Method 2007, Condition A

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### MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Output Enable (OE)
2	Do Not Connect
3	Case/Ground
4	Output
5	Do Not Connect
6	Supply Voltage

LINE	MARKING
1	<b>E11.113</b> <i>E=Ecliptek Designator</i>
2	<b>XXXXX</b> <i>XXXXX=Ecliptek Manufacturing Identifier</i>

### Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

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## OUTPUT WAVEFORM & TIMING DIAGRAM



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## Test Circuit for CMOS Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C<sub>L</sub> includes sum of all probe and fixture capacitance.

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## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

<b><math>T_s</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s$ MIN)	150°C
- Temperature Typical ( $T_s$ TYP)	175°C
- Temperature Maximum ( $T_s$ MAX)	200°C
- Time ( $t_s$ MIN)	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_P</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

$T_s$ MAX to $T_L$ (Ramp-up Rate)	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s$ MIN)	N/A
- Temperature Typical ( $T_s$ TYP)	150°C
- Temperature Maximum ( $T_s$ MAX)	N/A
- Time ( $t_s$ MIN)	60 - 120 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum
<b>Peak Temperature (<math>T_P</math>)</b>	240°C Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	240°C Maximum 2 Times / 230°C Maximum 1 Time
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)